

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. through 36. (Cancelled)

37. (Currently Amended) ~~The~~A method of supplying a substrate in a chip mounting apparatus according to claim 36, further the method comprising:
transporting a substrate to a position above a stage via a conveyor;
moving the conveyor and stage toward each other so that the stage removes the substrate from the conveyor and supports the substrate above the conveyor for chip mounting; and
maintaining a volume around the stage with a positive air pressure to maintain a clean environment.

38. (Currently Amended) ~~The~~A method of supplying a substrate in a chip mounting apparatus according to claim 36, the method comprising:
transporting a substrate to a position above a stage via a conveyor; and
moving the conveyor and stage toward each other so that the stage removes the substrate from the conveyor and supports the substrate above the conveyor for chip mounting,
wherein the movement of the conveyor and stage toward each other is provided by movement of the conveyor while the stage remains stationary.

39. (Canceled)

40. (Currently Amended) ~~The~~A method of supplying a substrate in a chip mounting apparatus according to claim 36, the method comprising:
transporting a substrate to a position above a stage via a conveyor; and
moving the conveyor and stage toward each other so that the stage removes the substrate from the conveyor and supports the substrate above the conveyor for chip mounting,

wherein the conveyor is of a concave shape with a through hole in a bottom surface thereof, so that the concave shape supports a perimeter of the substrate and the through hole allows passage of a portion of the stage.

41. (Currently Amended) ~~The~~A method of supplying a substrate in a chip mounting apparatus according to claim 36, the method~~further~~ comprising:
transporting a substrate to a position above a stage via a conveyor;
moving the conveyor and stage toward each other so that the stage removes the substrate from the conveyor and supports the substrate above the conveyor for chip mounting; and

activating a stopper to stop the movement of the substrate when it reaches a position above the stage.

42. - 45. (Canceled)

46. (Currently Amended) The method of supplying a substrate in a chip mounting apparatus according to claim 45, further the method comprising:
removably holding the substrate in a substrate carrier;
transporting the substrate carrier to a position above a stage;
moving the substrate carrier and stage toward each other so that the stage removes the substrate from the substrate carrier and supports the substrate above the substrate carrier for chip mounting; and
maintaining a volume around the stage with a positive air pressure to maintain a clean environment.

47. (Currently Amended) The method of supplying a substrate in a chip mounting apparatus according to claim 45, the method comprising:
removably holding the substrate in a substrate carrier;
transporting the substrate carrier to a position above a stage; and
moving the substrate carrier and stage toward each other so that the stage removes the substrate from the substrate carrier and supports the substrate above the substrate carrier for chip mounting,
wherein the movement of the substrate carrier and stage toward each other is provided by movement of the substrate carrier while the stage remains stationary.

48. (Currently Amended) The method of supplying a substrate in a chip mounting apparatus according to claim 45, the method comprising:
removably holding the substrate in a substrate carrier;
transporting the substrate carrier to a position above a stage; and
moving the substrate carrier and stage toward each other so that the stage removes the substrate from the substrate carrier and supports the substrate above the substrate carrier for chip mounting,

wherein the movement of the substrate carrier and stage toward each other is provided by movement of the stage while the substrate carrier remains stationary.

49. (Currently Amended) The method of supplying a substrate in a chip mounting apparatus according to claim 45, the method comprising:
removably holding the substrate in a substrate carrier;
transporting the substrate carrier to a position above a stage; and
moving the substrate carrier and stage toward each other so that the stage removes the substrate from the substrate carrier and supports the substrate above the substrate carrier for chip mounting,

wherein the substrate carrier is of a concave shape with a through hole in a bottom surface thereof, so that the concave shape supports a perimeter of the substrate and the through hole allows passage of a portion of the stage.

50. (Currently Amended) The method of supplying a substrate in a chip mounting apparatus according to claim 45, the method further comprising:
removably holding the substrate in a substrate carrier;
transporting the substrate carrier to a position above a stage;
moving the substrate carrier and stage toward each other so that the stage removes the substrate from the substrate carrier and supports the substrate above the substrate carrier for chip mounting; and
activating a stopper to stop the movement of the substrate when it reaches a position above the stage.

51. - 69. (Canceled)